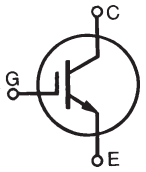
IXYS

High Voltage IGBT
For Capacitor Discharge Applications

(Electrically Isolated Tab)

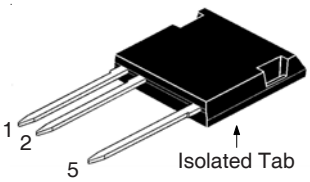
IXGF20N250

V_{CES} = 2500V
I_{C25} = 23A
$V_{CE(sat)}$ ≤ 3.1V



Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	2500	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	2500	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	T_C = 25°C	23	A
I_{C90}	T_C = 90°C	14	A
I_{CM}	T_C = 25°C, V_{GE} = 19V, 1ms	105	A
	10ms	55	A
SSOA	V_{GE}= 15V, T_{VJ} = 125°C, R_G = 20Ω	I_{CM} = 60	A
(RBSOA)	Clamped Inductive Load	1500	V
P_C	T_C = 25°C	100	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6 mm (0.062 in.) from Case for 10s	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
F_C	Mounting Force	20..120 / 4.5..27	Nm/lb.in.
V_{ISOL}	50/60Hz, 1 Minute	4000	V~
Weight		6	g

ISOPLUS i4-Pak™



1 = Gate 5 = Collector
2 = Emitter

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 4000V~ Electrical Isolation
- High Peak Current Capability
- Low Saturation Voltage
- Molding Epoxies Meet UL 94 V-0 Flammability Classification

Applications

- Capacitor Discharge
- Pulser Circuits

Advantages

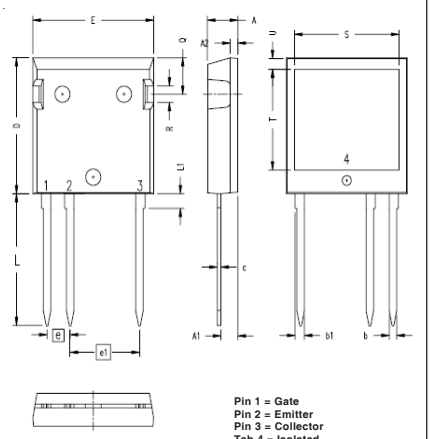
- High Power Density
- Easy to Mount

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{CES}	I_C = 250μA, V_{GE} = 0V	2500			V
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	3.0		5.0	V
I_{CES}	V_{CE} = 0.8 • V_{CES}, V_{GE} = 0V			10	μA
	Note 2, T_J = 125°C			750	μA
I_{GES}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
$V_{CE(sat)}$	I_C = 20A, V_{GE} = 15V, Note 1			3.1	V

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Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.
g_{fs}	I_C = 20A, V_{CE} = 10V, Note 1	8	13	S
$I_{C(ON)}$	V_{GE} = 20V, V_{CE} = 15V, Note 1		190	A
C_{ies}	V_{CE} = 15V, V_{GE} = 25V, f = 1MHz		1190	pF
C_{oes}			53	pF
C_{res}			18	pF
Q_g	I_C = 20A, V_{GE} = 15V, V_{CE} = 1000V		53	nC
Q_{ge}			8	nC
Q_{gc}			22	nC
$t_{d(on)}$	**Resistive Switching Times**		57	ns
t_r	I_C = 40A, V_{GE} = 15V		160	ns
$t_{d(off)}$	V_{CE} = 1250V, R_G = 10Ω		136	ns
t_f			930	ns
R_{thJC}				1.25 °C/W
R_{thCS}			0.15	°C/W
R_{thJA}			30	°C/W

ISOPLUS i4-Pak™ (HV) Outline



Pin 1 = Gate
Pin 2 = Emitter
Pin 3 = Collector
Tab 4 = Isolated

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.190	.205	4.83	5.21
A1	.102	.118	2.59	3.00
A2	.046	.085	1.17	2.16
b	.045	.055	1.14	1.40
b1	.058	.068	1.47	1.73
C	.020	.029	0.51	0.74
D	.819	.840	20.80	21.34
E	.770	.799	19.56	20.29
e	.150 BSC		3.81 BSC	
e1	.450 BSC		11.43 BSC	
L	.780	.840	19.81	21.34
L1	.083	.102	2.11	2.59
Q	.210	.244	5.33	6.20
R	.100	.180	2.54	4.57
S	.660	.690	16.76	17.53
T	.590	.620	14.99	15.75
U	.065	.080	1.65	2.03

Notes:

1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.
2. Device must be heatsunk for high temperature leakage current measurements to avoid thermal runaway.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,860,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405 B2 6,710,463 6,727,585 6,759,692 6,771,478 B2 7,005,734 B2 7,063,975 B2 7,071,537 7,157,338B2

Fig. 1. Output Characteristics @ T_J = 25ºC

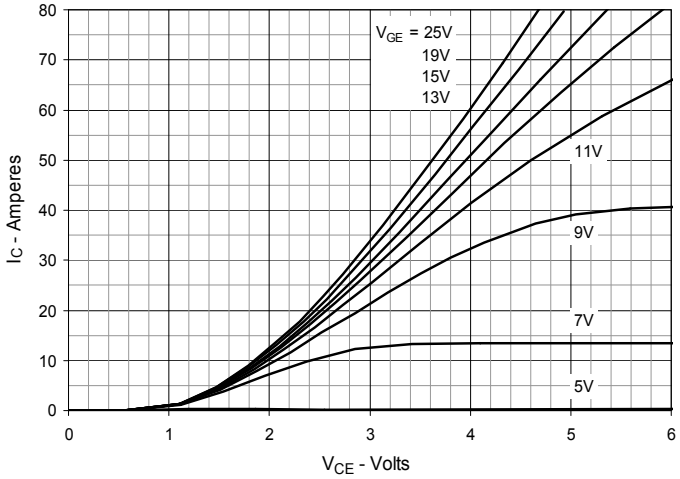


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

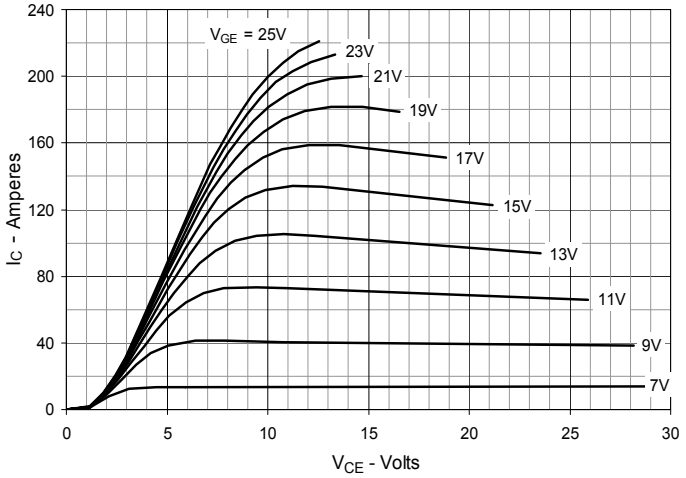


Fig. 3. Output Characteristics @ T_J = 125ºC

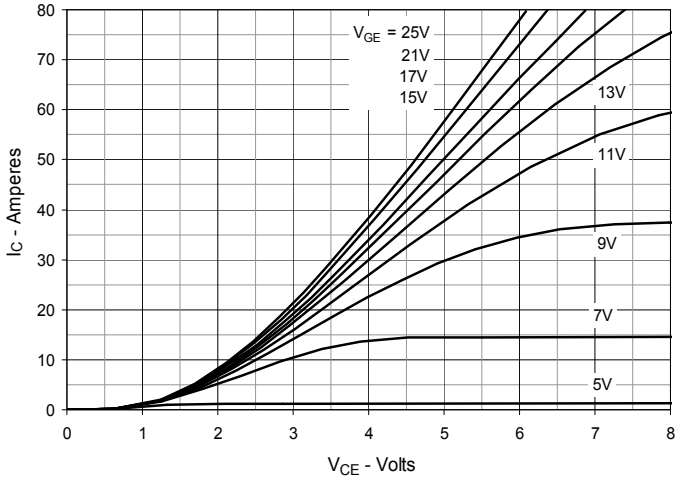


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

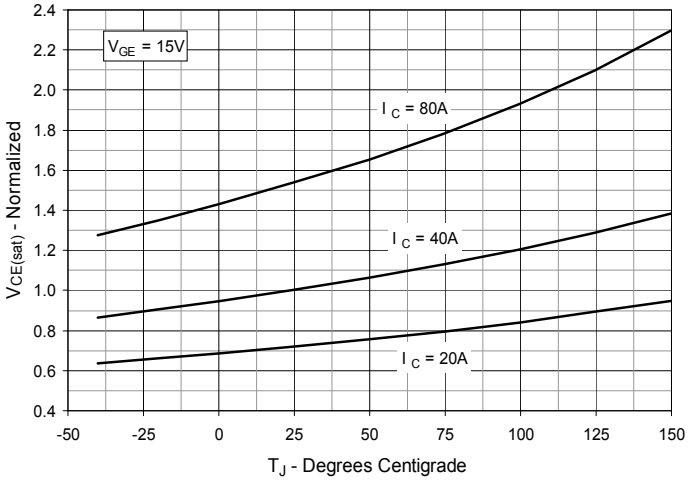


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

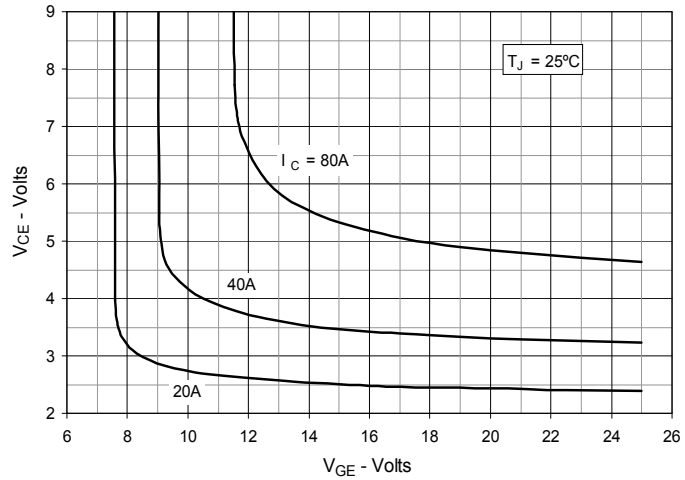
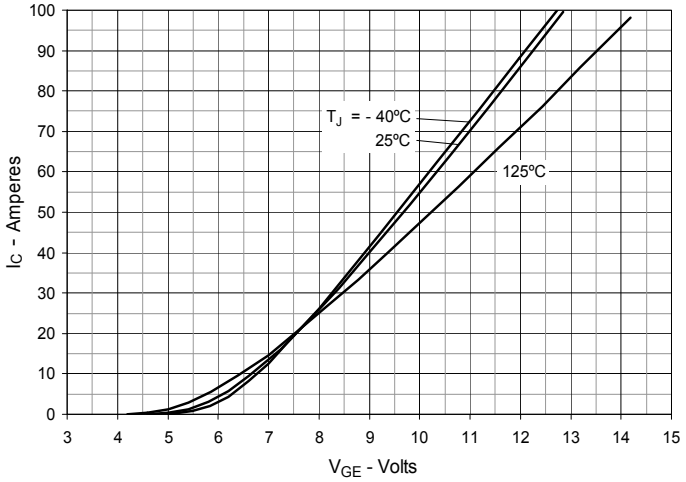


Fig. 6. Input Admittance



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Fig. 7. Transconductance

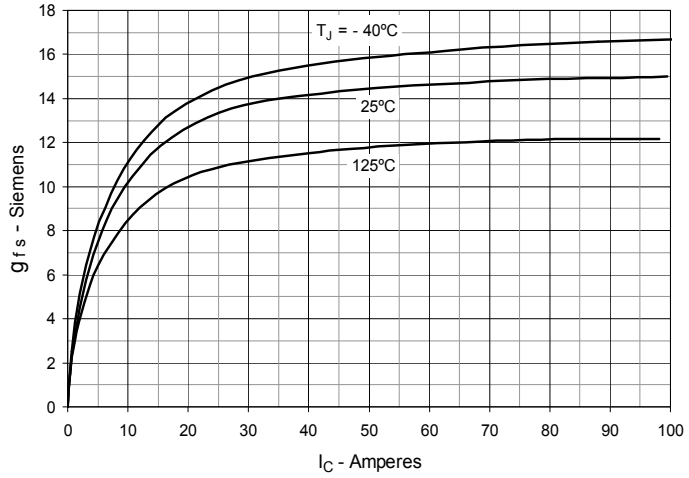


Fig. 8. Gate Charge

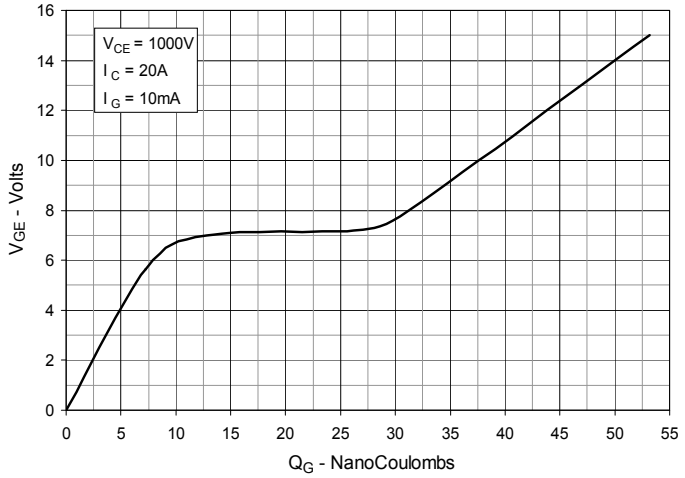


Fig. 9. Reverse-Bias Safe Operating Area

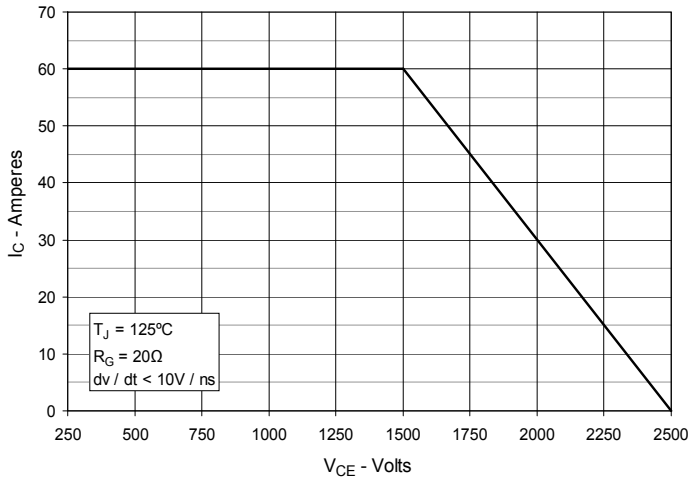


Fig. 10. Capacitance

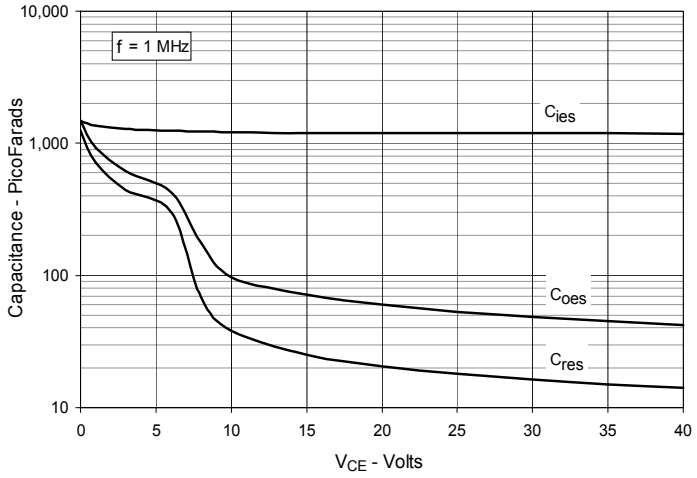
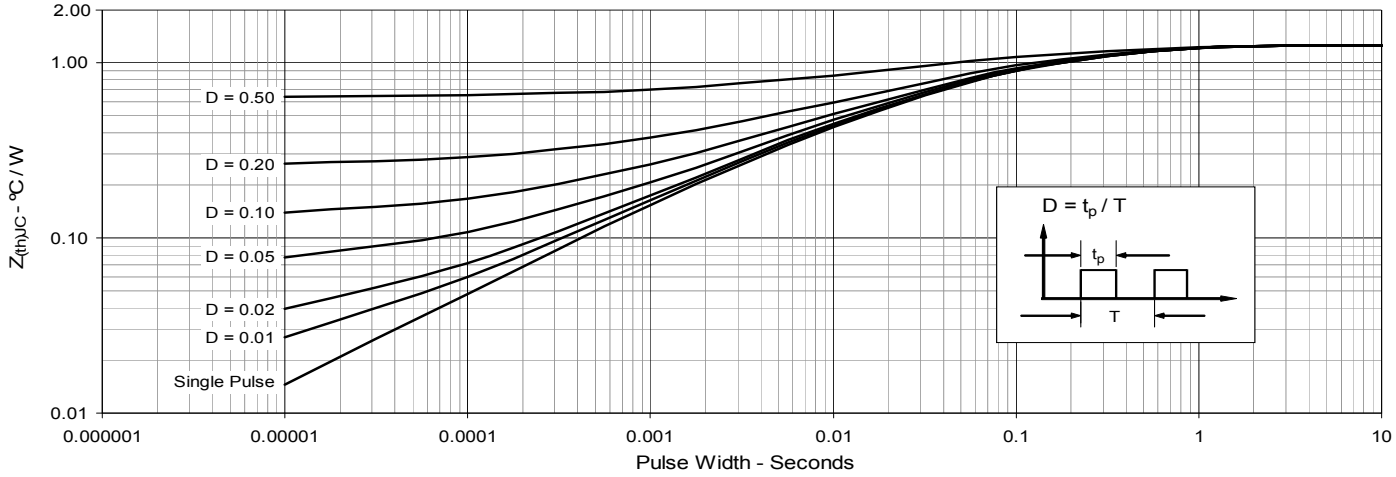


Fig. 11. Maximum Transient Thermal Impedance



IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

Fig. 12. Resistive Turn-on Rise Time vs. Junction Temperature

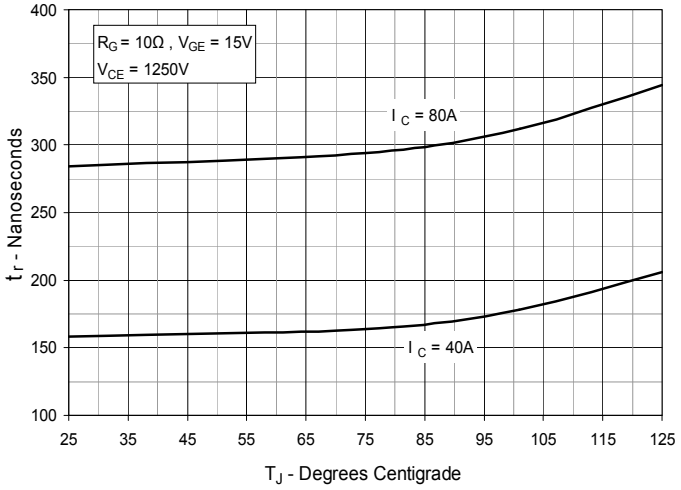


Fig. 13. Resistive Turn-on Rise Time vs. Collector Current

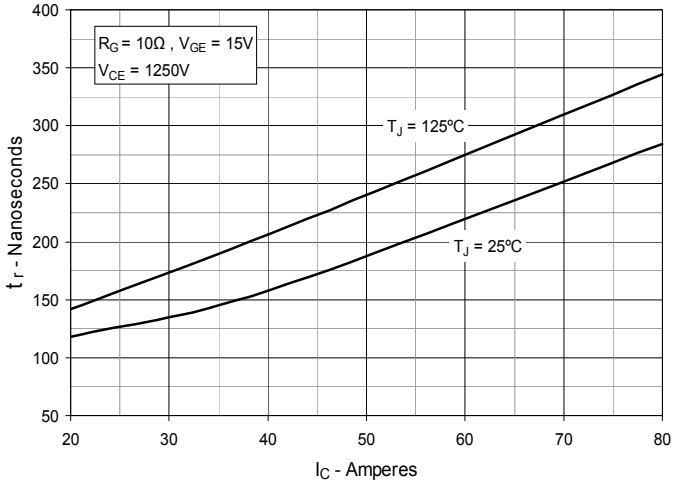


Fig. 14. Resistive Turn-on Switching Times vs. Gate Resistance

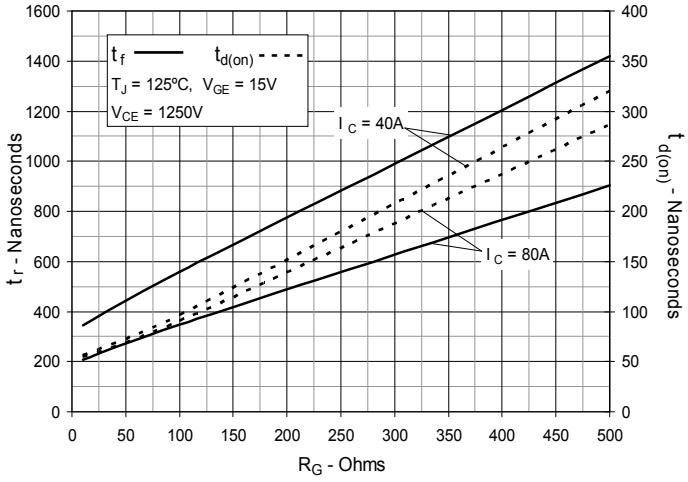


Fig. 15. Resistive Turn-off Switching Times vs. Junction Temperature

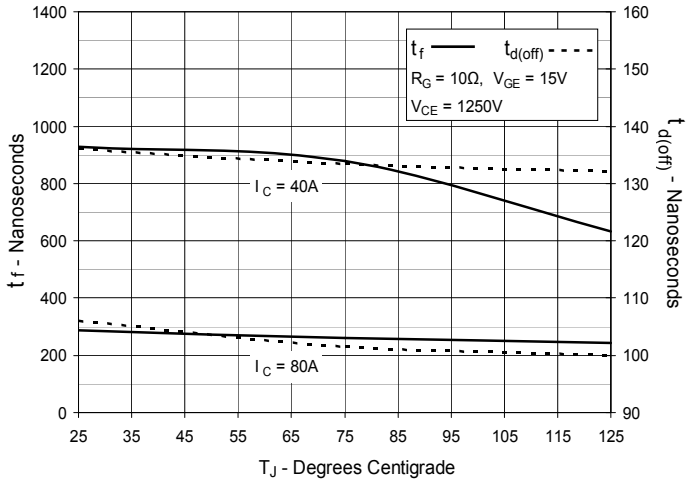


Fig. 16. Resistive Turn-off Switching Times vs. Collector Current

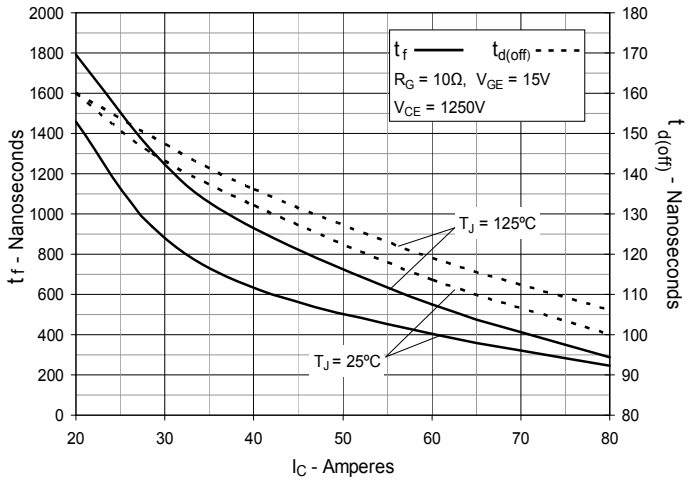
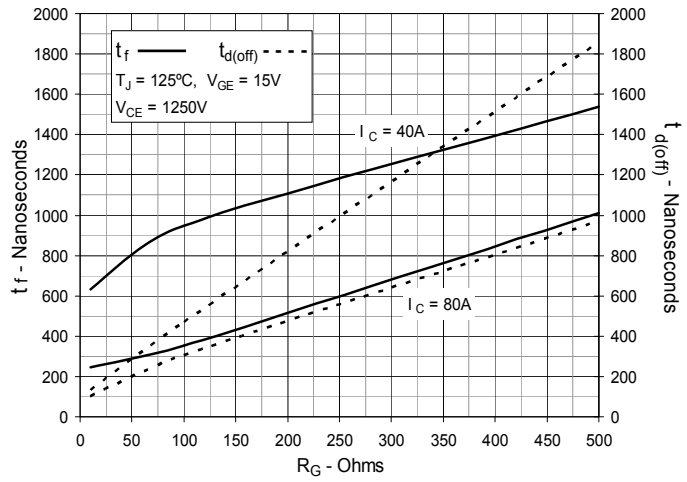


Fig. 17. Resistive Turn-off Switching Times vs. Gate Resistance



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